



**PATENT**

11/16  
10-15-98

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Reissue Application of: Heppler**

**Serial No.: 08/715,869**

**Filed: September 19, 1996**

**Title: METHOD AND APPARATUS FOR TESTING INTEGRATED CIRCUITS**

**Examiner: T. Nguyen**

**Group Art Unit: 3615**

**Attorney Docket No.: 2972US (92-0476RE)**

**CERTIFICATE OF MAILING**

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**RESPONSE TO FIRST OFFICE ACTION**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

In response to the Office Action mailed July 9, 1998, please amend the application as follows:

**IN THE SPECIFICATION**

In column 1, please change the paragraph in lines 14-34 to read as follows:

FIG. 1 illustrates a representative portion of a semiconductor chip trim and pin forming machine. One can purchase such a machine from ASM Asia Inc., 4302 E. Broadway Rd., Phoenix, Ariz., model AP50, or from Precision Technologies Inc. 1725 De La Cruz Blvd. #4, Santa Clara, Calif. 95050, models Matrix SS, FS, or FM. FIG. 1 identifies the following elements: Platen 40 is the portion of the press-type machine to moved up and down to stamp in the desired forming and trimming operations. Vertical action rod 42 is attached to a means for moving platen 40 into contact with the non movable table 44. IC forming and cutting die [44] 45 are mounted to both the platen 40 and table 44. IC loading station 50 receives a set of ICs usually from the plastic encapsulation station and they are attached on a typical single leadframe. Trim stations 60 will trim off the excess encapsulation material and metal leadframe portions. Forming stations 70 will bend the leads of the ICs into various configurations like "SOJ" or DIP.

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